

TECHNICAL DATA

Manufacturers of a wide range of electrical and electronic servicing products, including cleaners, solvents, lubricants, greases, freezers, air dusters, lacquers, coatings and de-soldering aids.



HEAT SINK COMPOUND FOR THERMAL COUPLING AND HEAT DISSIPATION

HEAT SINK COMPOUND is a highly thermally conductive silicone grease. This, together with a low moisture and metallic impurity content, make it suitable for a wide variety of applications within the electrical components industry.

APPLICATIONS

Used within a semi-conductor device case it affords excellent shock protection for the transistor or diode elements and provides protection against inadvertent contamination of these elements before the devices are finally encapsulated. Also acts as an excellent moisture buffer.

Heat Sink Compound also finds use as a contact material when mounting semi-conductor devices on heat-sinks, obviating air gaps between imperfectly mating surfaces. In this application, it may be used in conjunction with electrically insulating mica washers without increasing the electrical leakage in any way. Indeed, in many cases insulation may be improved.

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| Appearance | : White, thixotropic paste |
| Odour | : Almost odourless |
| SG | : 2.3 |
| Evaporation | : 7 days at room temperature, 0.02% 24 hours at 150°C, 0.2% |
| Dielectric strength | : 10 kv/mm |
| Permittivity, 1 MHz | : 4.3 |
| Power factor, 1 MHz | : 3.3×10^{-3} |
| Volume resistivity | : At room temperature, 1.1×10^{15} ohm.cm |
| Thermal conductivity | : At 40°C, 16.7×10^{-4} cal/cm.sec, °C |
| Temperature range | : Operational from -50°C to + 200°C |
| Solubility | : Insoluble in water, soluble in some solvents |
| Flammability | : Not classified as flammable |
| Packaging | : 25gm tube (50 per carton) |